WHAT IS CLAIMED IS:

1. A method for determining a sequence in which microstructures are to be processed at a laser-processing site, the method comprising:

receiving reference data which represent locations of microstructures to be processed at the site;

coalescing adjacent groups of microstructures into clusters of microstructures including edge clusters which contain microstructures located near travel limits of a motor-driven stage which moves the microstructures relative to a laser beam at the site;

dividing a cluster fragment from each edge cluster wherein the cluster fragments contain the microstructures located near the travel limits; and

sorting the clusters and cluster fragments to obtain data which represent a substantially optimum sequence in which the microstructures are to be processed to increase throughput at the site.

2. The method as claimed in claim 1 wherein the step of sorting is based on energy expended in at least one coil of at least one motor in response to motor commands.

3. The method as claimed in claim 1 wherein each of the cluster and cluster fragments has a plurality of possible processing directions and wherein the step of sorting includes the step of determining a substantially optimum direction in which to process the microstructures.

4. The method as claimed in claim 1 wherein the step of sorting includes the steps of selecting a substantially optimum cluster or cluster fragment to be initially processed at the site, then determining a plurality of possible sequences for processing the remaining clusters and cluster fragments and selecting a substantially optimum sequence from the plurality of possible sequences.

5. The method as claimed in claim 1 wherein the microstructures are located on dice of a wafer.

6. A subsystem for determining a sequence in which microstructures are to be processed at a laser-processing site, the subsystem comprising:

means for receiving reference data which represent locations of microstructures to be processed at the site;

means for coalescing adjacent groups of microstructures into clusters of microstructures including edge clusters which contain microstructures located near travel limits of a motor-driven stage which moves the microstructures relative to a laser beam at the site;

means for dividing a cluster fragment from each edge cluster wherein the cluster fragments contain the microstructures located near the travel limits; and

means for sorting the clusters and cluster fragments to obtain data which represent a substantially optimum sequence in which the microstructures are to be processed to increase throughput at the site.

7. The subsystem as claimed in claim 6 wherein the means for sorting sorts based on energy expended in at least one coil of at least one motor in response to motor commands.

8. The subsystem as claimed in claim 6 wherein each of the clusters and cluster fragments has a plurality of possible processing directions and wherein the means for sorting includes means for determining a substantially optimum direction in which to process the microstructures.

9. The subsystem as claimed in claim 6 wherein the means for sorting includes means for selecting a substantially optimum cluster or cluster fragment to be initially processed at the site, for determining a plurality of possible sequences for processing the remaining clusters and cluster fragments and for selecting a substantially optimum sequence from the plurality of possible sequences.

10. The subsystem as claimed in claim 6 wherein the microstructures are located on dice of a wafer.

11. The subsystem as claimed in claim 10 wherein the microstructures are conductive lines of the dice.

12. The subsystem as claimed in claim 11 wherein the conductive lines are metal lines.

13. The subsystem as claimed in claim 11 wherein the dice are semiconductor memory devices and wherein the conductive lines are to be ablated at the site to repair defective memory cells of the devices.

14. The subsystem as claimed in claim 6 wherein the microstructures are parts of a semiconductor device.

15. The subsystem as claimed in claim 14 wherein the semiconductor device is a microelectromechanical device.

16. The subsystem as claimed in claim 14 wherein the semiconductor device is a silicon semiconductor device.

17. The subsystem as claimed in claim 14 wherein the semiconductor device is a semiconductor memory.

18. The subsystem as claimed in claim 6 wherein the microstructures are parts of a microelectronic device.

19. The subsystem as claimed in claim 6 wherein the microstructures in each group have a substantially common pitch.

20. The subsystem as claimed in claim 7 wherein the stage is an x-y stage and wherein the means for sorting sorts based on energy expended in a plurality of coils of a plurality of motors in response to motor commands.